Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
			* : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	17-10-2023
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Material Declaration champion	Representative Title	Material Declaration champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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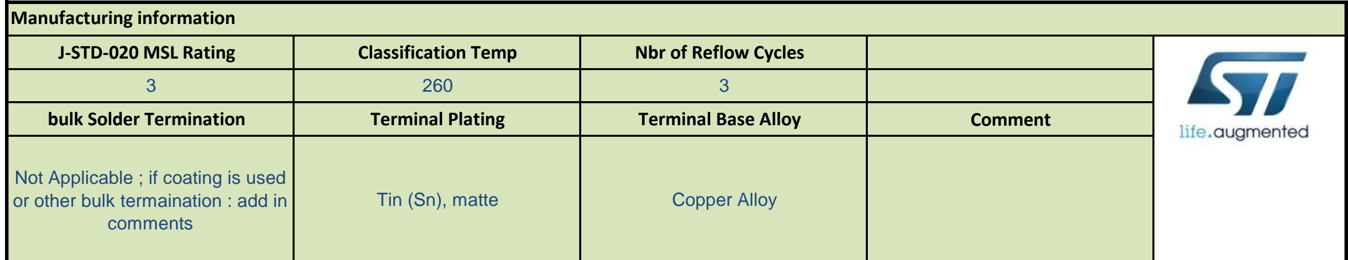
Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as omprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	**Mfr Item Name**	**Version**	**Mfr Site**	**Date**
STM32H7S7I8T6	E31T*485XXXY	A	9991	17-10-2023
	Amount	UoM	**Unit type**	**ST ECOPACK Grade**
	1650.00	mg	Each	ECOPACK® 2
.	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		



Manufacturing information				
J-STD-020 MSL Rating	**Classification Temp**	**Nbr of Reflow Cycles**		life.augmented
3	260	3		
bulk Solder Termination	**Terminal Plating**	**Terminal Base Alloy**	**Comment**	
Not Applicable ; if coating is used or other bulk termaination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	24x24	176	L bend	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	**Response**
1 - Product(s) meets EU RoHS requirement without any exemptions	**TRUE**
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE

Exemption Id.	**Description**

QueryList : REACH-14th June 2023				
Query				**Response**
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				**TRUE**
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	E31T*485XXXY				6000000.0	1000001.4
Homogeneous Material	**Material Group**	**Mass**	**UoM**	**Level**	**Substance Category**	**Substance**	**CAS**	**Exempt**	**Mass**	**UoM**	**Concentration in homogeneous material (ppm)**	**Concentration in product (ppm)**
Die or dies	M-011 Other inorganic materials	10.501	mg	supplier	die	Silicon (Si)	7440-21-3		10.029	mg	955052	6078
				supplier	metallization	Aluminium (Al)	7429-90-5		0.056	mg	5333	34
				supplier	metallization	Copper (Cu)	7440-50-8		0.175	mg	16665	106
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	95	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	2762	18
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	476	3
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	95	1
				supplier	Passivation	Silicon Oxide	7631-86-9		0.205	mg	19522	124
Leadframe (C7025 + Ag + R970)	Copper & its alloys	425.000	mg	supplier	Leadframe	Copper(Cu)	7440-50-8		385.178	mg	906300	233441
				supplier	Leadframe	Nickle (Ni)	7440-02-0		12.920	mg	30400	7830
				supplier	Leadframe	Silicon (Si)	7440-21-3		4.845	mg	11400	2936
				supplier	Leadframe	Magnesium (Mg)	7439-95-4		1.233	mg	2900	747
				supplier	Leadframe	Silver(Ag)	7440-22-4		14.875	mg	35000	9015
				supplier	Leadframe	Polyimide	Proprietary		2.380	mg	5600	1442
				supplier	Leadframe	Poly–ethylene–terephthalate	25038-59-9		1.785	mg	4200	1082
				supplier	Leadframe	NBR	9003-18-3		0.595	mg	1400	361
				supplier	Leadframe	Bismaleimide	79922-55-7		0.595	mg	1400	361
				supplier	Leadframe	Phenol resin	28453-20-5		0.595	mg	1400	361
Glue epoxy (YIZ 8143)	Precious metals	2.600	mg	supplier	Glue or tape	Silver Flake	7440-22-4		2.015	mg	775000	1221
				supplier	Glue or tape	Epoxy Acylate	15625-89-5		0.130	mg	50000	79
				supplier	Glue or tape	Substiyuted Polyamine	68490-66-4		0.039	mg	15000	24
				supplier	Glue or tape	Bisphenol F EPOXY RESIN	28064-14-4		0.260	mg	100000	158
				supplier	Glue or tape	2-Ethylhexyl glycidyl ether	2461-15-6		0.156	mg	60000	95
Bonding wire (Au)	Precious metals	5.400	mg	supplier	Bonding wire	Gold	7440-57-5		5.338	mg	988500	3235
				supplier	Bonding wire	Palladium	7440-05-3		0.062	mg	11500	38
Encapsulation (EME-G631SH)	M-011 Other inorganic materials	1190.605	mg	supplier	Molding Compound	2,2'-((3,3',5,5'-Tetramethyl-(1,1'-biphenyl)-4,4	85954-11-6		47.624	mg	40000	28863
				supplier	Molding Compound	Epoxy Resin	Proprietary		23.812	mg	20000	14432
				supplier	Molding Compound	Phenol Resin	Proprietary		89.295	mg	75000	54118
				supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		934.030	mg	784500	566079
				supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		89.295	mg	75000	54118
				supplier	Molding Compound	Carbon Black	1333-86-4		6.548	mg	5500	3969
External Plating (Sn)	M-011 Other inorganic materials	15.895	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		15.893	mg	999900	9632
				supplier	Matte Sn	Impurities	-		0.002	mg	100	1